



SUPER FAST DIODE MODULE TYPE 2X60A

Features

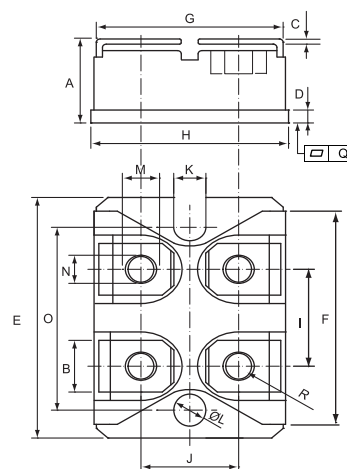
- High Surge Capability
- Type 1000V V_{RRM}
- Isolation Type Package
- Electrically Isolation base plate
- RoHS compliant



Maximum Ratings

Operating Temperature : -55 °C to +175 °C
 Storage Temperature : -55 °C to +175 °C

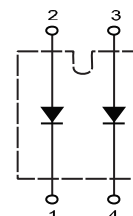
Part Number	Maximum Recurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
MURI2X60-10A	1000V	700V	1000V



Electrical Characteristics @ 25 °C Unless Otherwise Specified.

Average Forward Current	$I_{F(AV)}$	60 A	$T_c=125\text{ }^\circ\text{C}$
Peak Forward Surge Current	I_{FSM}	900 A	8.3ms, half sine
Maximum Instantaneous Forward Voltage*	V_F	2.35 V	$I_{FM}=60\text{A}; T_J=25\text{ }^\circ\text{C}$
Maximum Instantaneous Reverse Current At Rated DC Blocking Voltage*	I_R	25 uA 3mA	$T_J=25\text{ }^\circ\text{C}$ $T_J=150\text{ }^\circ\text{C}$
Maximum Reverse Recovery Time	T_{rr}	90 ns	$I_F=0.5\text{A}, I_R=1.0\text{A}$ $I_{RR}=0.25\text{A}$
Isolation Voltage	V_{iso}	2500 V	A.C. 1 minute
Maximum Thermal Resistance Junction To Case	$R_{\theta jc}$	0.8 °C/W	
Mounting torque	N-m	1.3	M4 Screw

* Pulse Test: Pulse Width 300 μ sec, Duty < 2%



MURI 2X60 xxA

	DIMENSIONS			
	INCHES		MM	
	MIN	MAX	MIN	MAX
A	0.460	0.483	11.68	12.28
B	0.307	0.323	7.80	8.20
C	0.030	0.033	0.75	0.85
D	0.071	0.081	1.80	2.05
E	1.488	1.504	37.80	38.20
F	1.248	1.260	31.70	32.00
G	0.917	0.957	23.30	24.30
H	0.996	1.008	25.30	25.60
I	0.579	0.602	14.70	15.30
J	0.492	0.516	12.50	13.10
K	0.161	0.169	4.10	4.30
L	0.161	0.169	4.10	4.30
M	0.181	0.197	4.60	5.00
N	0.165	0.181	4.20	4.60
O	1.181	1.197	30.00	30.40
Q	-0.002	0.004	-0.05	0.10
R	M4*8			



Figure .1- Typical Forward Characteristics

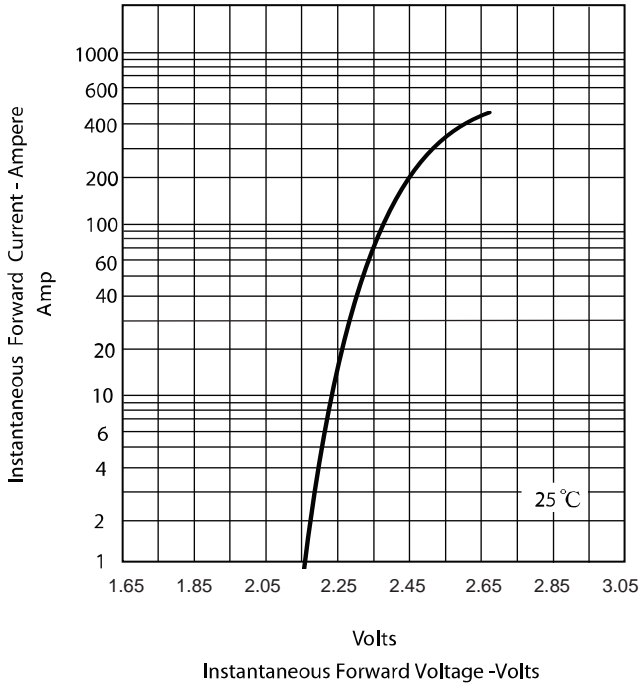


Figure.2 - Forward Derating Curve

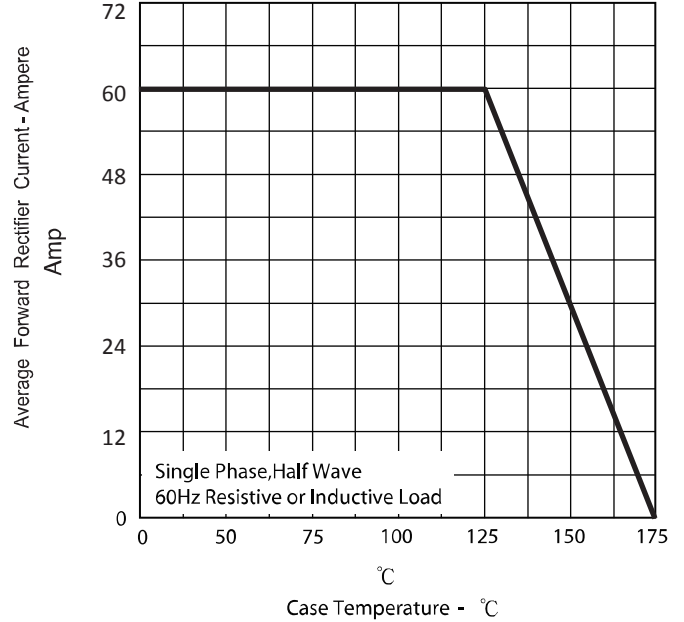


Figure.3 - Peak Forward Surge Current

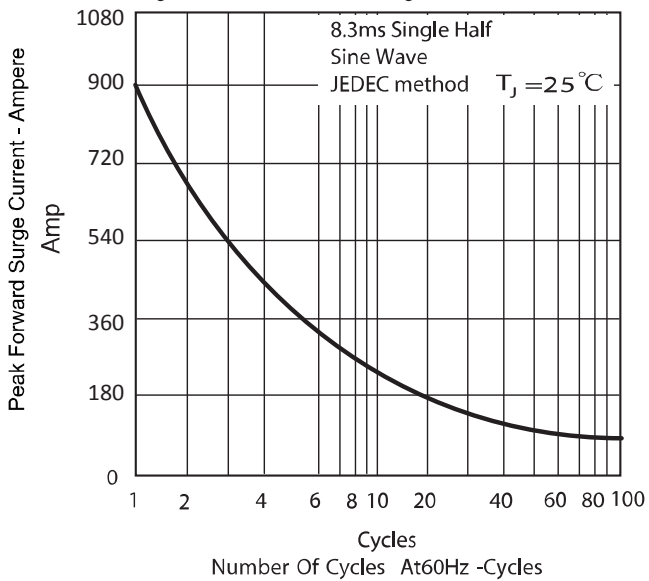
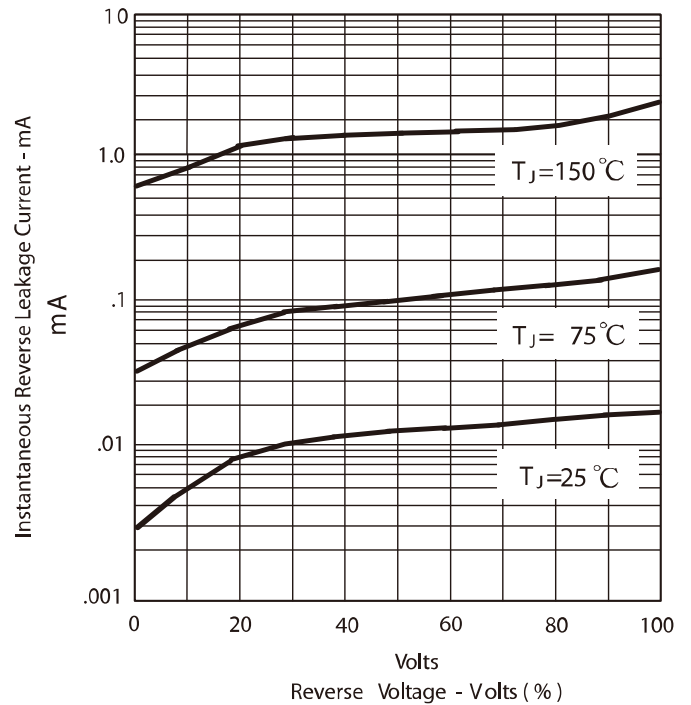


Figure .4 -Typical Reverse Characteristics





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